

BZT52C2V0S-BZT52C51S

FEATURES

- Planar die construction
- General purpose, medium current



Ideally suited for automated assembly processes

Cathode Anode 2 Anode 2 SOD-323

APPLICATIONS

- Zener diode
- Ultra-small surface mount package

ORDERING INFORMATION

Type No. Marking Package Code

BZT52C2V0S-BZT52C51S See table 2 SOD-323

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F =10mA	V _F	0.9	V
Power Dissipation	P _d	200	mW
Thermal resistance, junction to ambient air	$R_{ heta j A}$	625	°C/W
Junction temperature	Tj	150	$^{\circ}$
Storage temperature range	T _{stg}	-65 to +150	$^{\circ}$

Notes: 1. Valid provided that device terminals are kept at ambient temperature.

- 2. Short duration test pulse used in minimize self-heating effect.
- 3. f = 1KHz.



BZT52C2V0S-BZT52C51S

ELECTRICAL CHARACTERISTICS @ Ta=25 $^{\circ}$ C unless otherwise specified

Type Number Marking Code		Zener Voltage Range			Maximum Zener Impedance		Maximum Reverse Current		Temperature Coefficient of zener voltage @			
		Vz@I _{ZT}		I _{ZT}	Zzt@lzt Zzk@lzk lzk		I _{ZK}	I _R	@V _R I _{ZTC} mV/°C		c mV/℃	
		Nom(V)	Min(V)	Max(V)	mA	0	Ω	mA	μA	V	Min	Max
BZT52C2V0S	WY	2.0	1.91	2.09	5	100	600	1.0	150	1.0	-3.5	0
BZT52C2V4S	WX	2.4	2.2	2.60	5	100	600	1.0	50	1.0	-3.5	0
BZT52C2V7S	W1	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0
BZT52C3V0S	W2	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0
BZT52C3V3S	W3	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0
BZT52C3V6S	W4	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0
BZT52C3V9S	W5	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0
BZT52C4V3S	W6	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0
BZT52C4V7S	W7	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2
BZT52C5V1S	W8	5.1	4.8	5.4	5	60	480	1.0	2	2.0	-2.7	1.2
BZT52C5V6S	W9	5.6	5.2	6.0	5	40	400	1.0	1	2.0	-2.0	2.5
BZT52C6V2S	WA	6.2	5.8	6.6	5	10	150	1.0	3	4.0	0.4	3.7
BZT52C6V8S	WB	6.8	6.4	7.2	5	15	80	1.0	2	4.0	1.2	4.5
BZT52C7V5S	WC	7.5	7.0	7.9	5	15	80	1.0	1	5.0	2.5	5.3
BZT52C8V2S	WD	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2
BZT52C9V1S	WE	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0
BZT52C10S	WF	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0
BZT52C11S	WG	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0
BZT52C12S	WH	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0
BZT52C13S	WI	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0
BZT52C15S	WJ	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0
BZT52C16S	WK	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0
BZT52C18S	WL	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0
BZT52C20S	WM	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0
BZT52C22S	WN	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0
BZT52C24S	WO	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0
BZT52C27S	WP	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3
BZT52C30S	WQ	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4
BZT52C33S	WR	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4
BZT52C36S	WS	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4
BZT52C39S	WT	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2
BZT52C43S	WU	43	40.0	46.0	5	100	700	1.0	0.1	32	10.0	12.0
BZT52C47S	WV	47	44.0	50.0	5	100	750	1.0	0.1	35	10.0	12.0
BZT52C51S	WW	51	48.0	54.0	5	100	750	1.0	0.1	38	10.0	12.0
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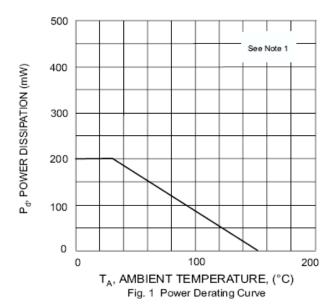


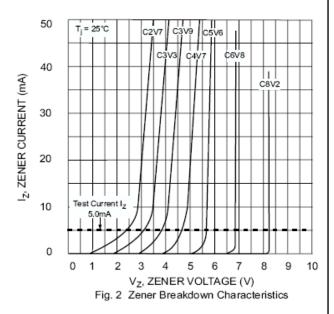
BZT52C2V0S-BZT52C51S

Notes: 1. Valid provided that device terminals are kept at ambient temperature.

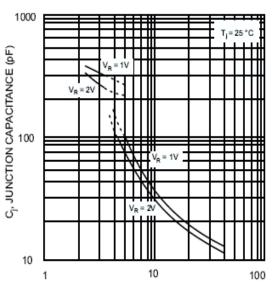
- 2. Tested with pulses, period=5ms, pulse width = 300µs.
- 3. f = 1KHz.

TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified





T_i = 25°C C10 C12 12, ZENER CURRENT (mA) 20 C18 Test current I-C33 C36 0 10 0 20 30 V2, ZENER VOLTAGE (V) Fig. 3 Zener Breakdown Characteristics



V₂, NOMINAL ZENER VOLTAGE (V) Fig. 4 Junction Capacitance vs Nominal Zener Voltage

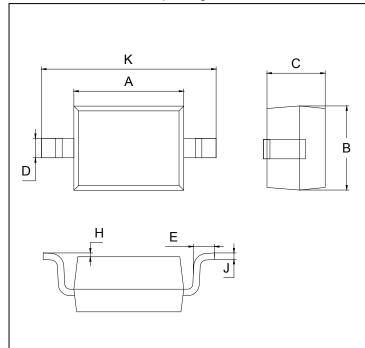


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PACKAGE OUTLINE

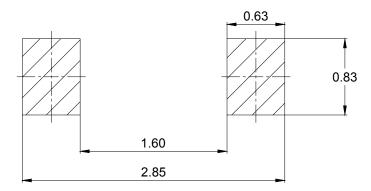
Plastic surface mounted package

SOD-323



SOD-323					
Dim	Min	Max			
Α	1.60	1.80			
В	1.20	1.40			
С	0.9 Typical				
D	0.30 Typical				
E	0.22	0.42			
Н	0.02	0.1			
J	0.1 Typical				
К	2.55	2.75			
All Dimensions in mm					

SOLDERING FOOTPRINT



Unit: mm

PACKAGE INFORMATION

Device	Package	Shipping
BZT52C2V0S-BZT52C51S	SOD-323	3000/Tape&Reel

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